IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re U.S. Patent Application of:

INVENTORS: Kim et al..
SERIAL NO.: 10/678,655 ART UNIT: N/A
FILED: October 2, 2003 EXAMINER: Not yet assigned
TITLE: Lead-Free Solder Alloys and Methods of Making Same
ATTORNEY DOCKET NO.: 873.0125.U1(US)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT
(37 C.F.R. §1.97(b))

Dear Sir:

Pursuant to Sections 609 and 707.05(b) of the MPEP and 37 CFR 1.97-1.99, copies are herewith submitted of documents which may be pertinent to the invention as claimed in the above-identified application. The attached form PTO-1449 lists these documents.

The filing of this Statement is not to be construed as a representation that a search has been made regarding the claimed invention (37 C.F.R. §1.97(g)) or that no other possible material information exists. In addition, the filing of this Statement is not to be construed to be an admission that the information cited in the Statement is, or is considered to be, material to Patentability (37 C.F.R. §1.97(h)).

Respectfully submitted,

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail on the date shown below in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

1/8/2004
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INFORMATION DISCLOSURE CITATION FORM FOR PATENT APPLICATION (FORM PTO-1449) (Substitute)	Docket No.: 873.0125.U1(US) Serial No.: 10/678,655 Applicant(s): Kim et al. Filing Date: 10/2/2003 Group:

PTO JC73 JAN 12 2004 PATENT & TRADEMARK OFFICE

U.S. PATENT DOCUMENTS

Examiner Initials	Document Number (Number-Kind Code)	Publication Date (MM-DD-YYYY)	Name of Patentee or Applicant	Class	Sub-class
	US-				
	US-				
	US-				
	US-				
	US-				
	US-				
	US-				
	US-				

FOREIGN PATENT DOCUMENTS

Examiner Initials	Document Number (Country Code-Number-Kind Code)	Publication Date (MM-DD-YYYY)	Name Of Patentee of Applicant	Translation? Yes/No/n/a
	- -			
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OTHER DOCUMENTS (Author (Capitalize), Title, Date, Pages, Etc., if known)

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	"Fast dissolution and soldering reactions on Au foils", Kim, P.G., et al., Materials Chemistry and Physics 53, 1998, pp. 165-171
	"A Thermodynamic Assessment Of The Au-Cu System", Sundman, Bo, Calphad Vol. 22, No. 3, 1998, pp. 335-354
	"No. 14 – Enthalphies De Formation Des Alliages Liquides Bismuth-Etain-Gallium A 723K. Choix D'Une Representation Analytique, Des Grandeurs D'Exces Integrales Et Partielles De Melange", Muggianu, Y.-M. et al., Journal De Chimie Physique, 1975, pp. 83-88
	"A Thermodynamic Evaluation Of The Au-Sn System", Chevallier, P.-Y., Elsevier Science Publishers B.V., 1988, pp. 1-13
	"Experimental and Calculated Ag + Au + Ge Phase Diagram", Hassam, S., et al., Metallurgical Transactions, Vol. 19A, March 1988, pp. 409-416
	"Experimental and Thermodynamic Assessment of Sn-Ag-Cu Solder Alloys", Journal of Electronic Materials, Vol. 29, No. 10, 2000, pp. 1122-1136

Examiner's Signature:	Date Considered:

Initial if reference was considered, whether or not citation is in conformance with MPEP. Mark through citation if not considered. Include a copy of this citation form with your next correspondence to the Applicant(s).